



Material Content Data Sheet



Sales Product Name		IPB014N06N		Issued		20. July 2018		
MA#		MA001652686						
Package		PG-TO263-7-3		Weight*		1523.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.699	0.24	0.24	2427	2427
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	iron	7439-89-6	0.803	0.05		527	
	non noble metal	copper	7440-50-8	801.714	52.61	52.68	526073	526758
	non noble metal	aluminium	7429-90-5	13.997	0.92	0.92	9184	9184
wire	non noble metal	aluminium	7429-90-5	13.997	0.92	0.92	9184	9184
encapsulation	organic material	carbon black	1333-86-4	8.717	0.57		5720	
	plastics	epoxy resin	-	95.891	6.29		62922	
	inorganic material	silicondioxide	60676-86-0	476.549	31.27	38.13	312705	381347
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8082	8082
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	177	178
solder	non noble metal	tin	7440-31-5	0.068	0.00		45	
	noble metal	silver	7440-22-4	0.085	0.01		56	
	non noble metal	lead	7439-92-1	3.258	0.21	0.22	2138	2239
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	6.97	6.98	69694	69785
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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